



Material Content Data Sheet



Sales Product Name		BTS7008-1EPA		Issued		4. July 2019		
MA#		MA005298550						
Package		PG-TSDSO-14-22		Weight*		65.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.856	1.32	1.32	13159	13159
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		580	
	non noble metal	iron	7439-89-6	0.754	1.16		11593	
wire	non noble metal	copper	7440-50-8	30.617	47.07	48.30	470742	483060
	non noble metal	copper	7440-50-8	0.647	1.00	1.00	9954	9954
	encapsulation	organic material	carbon black	1333-86-4	0.088	0.14		1354
encapsulation	plastics	epoxy resin	-	3.433	5.28		52788	
	inorganic material	silicondioxide	60676-86-0	25.823	39.70	45.12	397035	451177
leadfinish	non noble metal	tin	7440-31-5	1.642	2.52	2.52	25240	25240
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12547	12547
glue	plastics	epoxy resin	-	0.055	0.09		851	
	noble metal	silver	7440-22-4	0.261	0.40	0.49	4012	4863
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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